ABSTRACT OF THE DISCLOSURE

To eliminate breakage of electronic parts or defective bonding, and enhance reliability of electronic parts, in regulation of electronic parts in bump bonding device. A bump bonding device comprising a stage 1 for mounting and heating an electronic part, and a position regulating device including a rotatable regulating plate 2 having a side for positioning the electronic part, a plate 4 having a side for positioning the electronic part in collaboration with the regulating plate, and a regulating spring 5 for applying a regulating force to the regulating plate in order to press the electronic part to the plate 4.